



#### N-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
30V	$28m\Omega$ @ $V_{GS} = 10V$	5.8A
	$42m\Omega$ @ $V_{GS} = 4.5V$	4.8A
	82mΩ @ V <sub>GS</sub> = 3V	2.0A

#### **Description**

This MOSFET has been designed to minimize the on-state resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

### **Applications**

- **Battery Charging**
- **Power Management Functions**
- DC-DC Converters
- Portable Power Adaptors

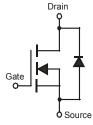
#### **Features and Benefits**

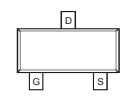
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 @3
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (approximate)







Top View

Internal Schematic

Top View

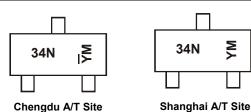
### Ordering Information (Note 4 & 5)

Part Number	Compliance	Case	Packaging
DMN3404L-7	Standard	SOT23	3000/Tape & Reel
DMN3404LQ-7	Automotive	SOT23	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead free.htmlfor more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product\_compliance\_definitions/.
- 5. For packaging details, go to Diodes website at http://www.diodes.com/products/packages.html.

## **Marking Information**



34N = Product Type Marking Code

YM = Date Code Marking for SAT (Shanghai Assembly/ Test site) YM = Date Code Marking for CAT (Chengdu Assembly/ Test site) Y or  $\overline{Y}$  = Year (ex: A =  $\overline{2013}$ )

M = Month (ex: 9 = September)

Data Coda Kay

	ale Code Rey												
	Year	200	9	2010		2011	20	12	2013		2014	2	2015
	Code	W		Х		Υ		Z	Α		В		С
_													
	Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
	Code	1	2	3	4	5	6	7	8	9	0	N	D



### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage (Note	6 & 7)	$V_{DSS}$	30	V	
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	Steady State	$T_A = -40^{\circ}C$ $T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$	Ι <sub>D</sub>	4.6 4.2 3.0	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = 10V	Steady State	$T_A = -40^{\circ}C$ $T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$	Ι <sub>D</sub>	6.2 5.8 4.0	Α
Continuous Drain Current (Note 7) V <sub>GS</sub> = 4.5V	Steady State	$T_A = -40^{\circ}C$ $T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$	Ι <sub>D</sub>	5.2 4.8 3.2	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = 3V	Steady State	$T_A = -40$ °C $T_A = +25$ °C $T_A = +85$ °C	Ι <sub>D</sub>	2.2 2.0 1.0	А
Pulsed Drain Current			I <sub>DM</sub>	30	Α

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	$P_{D}$	0.72	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C	R <sub>θJA</sub>	173	°C/W
Power Dissipation (Note 7)	P <sub>D</sub>	1.4	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C	$R_{\theta JA}$	90	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

<sup>6.</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.7. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

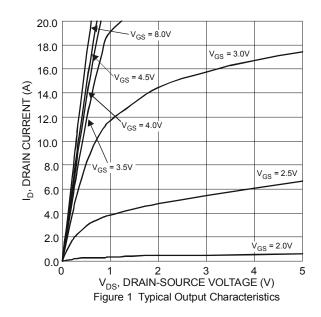


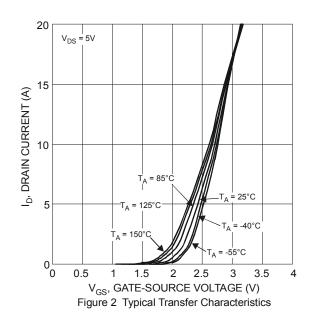
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	1.0	μΑ	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	1.5	2.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain Source On Decistones T = 40°C (Nets 0)	J	_	23	27	_	$V_{GS} = 4.5V, I_D = 4.8A$	
Static Drain-Source On-Resistance T <sub>J</sub> = -40°C ( <b>Note 9</b> )	R <sub>DS(ON)</sub>	_	57	74	_	V <sub>GS</sub> =3V, I <sub>D</sub> =2A	
		_	24	28		V <sub>GS</sub> = 10V, I <sub>D</sub> = 5.8A	
Static Drain-Source On-Resistance T <sub>J</sub> = +25°C	R <sub>DS(ON)</sub>	_	33	42	mΩ	$V_{GS} = 4.5V$ , $I_D = 4.8A$	
		_	63	82		V <sub>GS</sub> =3V, I <sub>D</sub> =2A	
Static Drain-Source On-Resistance T <sub>J</sub> = +85°C (Note 9)	R <sub>DS(ON)</sub>	_	71	95	mΩ	V <sub>GS</sub> =3V, I <sub>D</sub> =2A	
Forward Transfer Admittance	Y <sub>fs</sub>	_	10	_	S	V <sub>DS</sub> = 5V, I <sub>D</sub> = 5.8A	
Diode Forward Voltage	$V_{SD}$	_	0.75	1.0	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C <sub>iss</sub>	_	498	_	pF		
Output Capacitance	Coss	_	52	_	pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	45	_	pF		
Gate Resistance	$R_g$	_	1.75	2.8	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 3V)	$Q_g$	_	3.8	5.3	nC	$V_{GS} = 3V, V_{DS} = 15V, I_D = 1A$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	5.3	7.5	nC		
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	11.3	16	nC	V <sub>GS</sub> = 10V/4.5V, V <sub>DS</sub> = 15V,	
Gate-Source Charge	Qgs	_	1.4	_	nC	I <sub>D</sub> = 5.8A	
Gate-Drain Charge	$Q_{gd}$	_	2.1	_	nC	7	
Turn-On Delay Time	t <sub>D(on)</sub>	_	3.41	10	ns		
Turn-On Rise Time		_	6.18	13	ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V,	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	13.92	28	ns	$R_L = 2.6\Omega$ , $R_G = 3\Omega$	
Turn-Off Fall Time		_	2.84	10	ns		

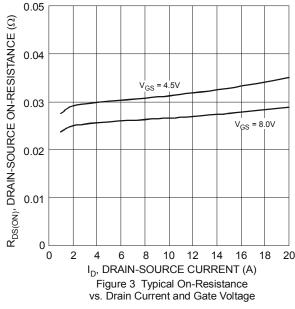
Notes:

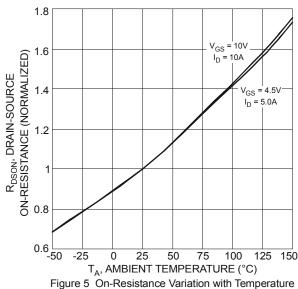
- 8. Short duration pulse test used to minimize self-heating effect.
  9. Guaranteed by design and 25°C data. Not subject to production testing 10. Guaranteed by design. Not subject to production testing.











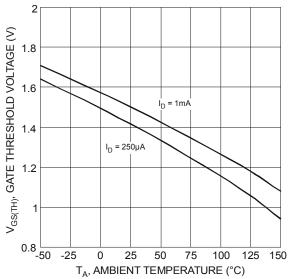


Figure 7 Gate Threshold Variation vs. Ambient Temperature

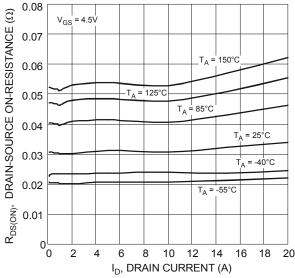


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

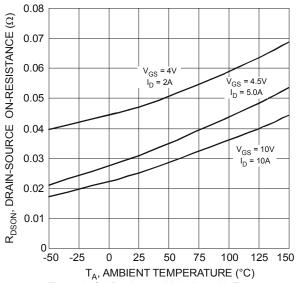


Figure 6 On-Resistance Variation with Temperature

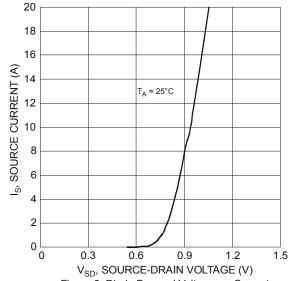
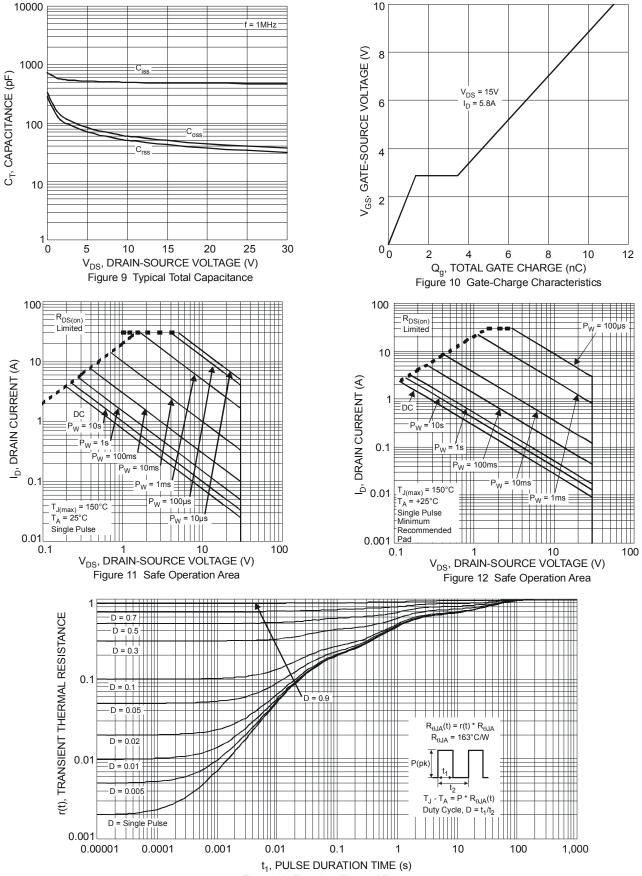


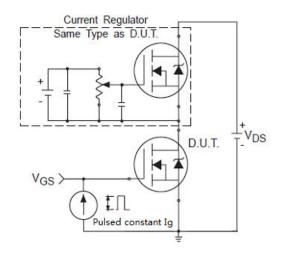
Figure 8 Diode Forward Voltage vs. Current

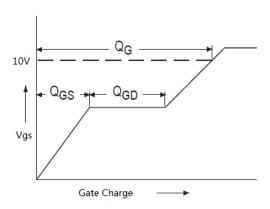




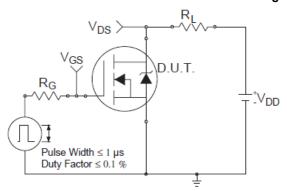


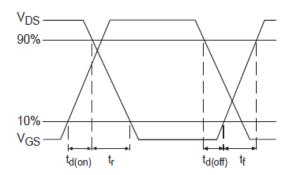
#### **Gate Charge Test Circuit and Waveform**





### **Switching Test Circuit and Waveform**

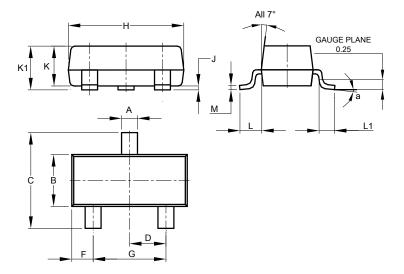






## **Package Outline Dimensions**

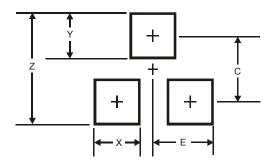
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
M	0.085	0.150	0.110				
α	α 8°						
All Dimensions in mm							

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35



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